

What is claimed is:

- 1 1. A display element comprising:
2 a glass substrate with an top surface on which a
3 luminescent body is formed;
4 a glass cap with a bottom surface on which the rim is
5 bonded to the rim of the top surface of the glass substrate
6 to create an airtight space; and
7 a sealing layer formed on the bonding region between the
8 glass substrate and the glass cap, wherein the sealing layer
9 is frit.
- 1 2. The display element according to claim 1, wherein the
2 sealing layer comprises spacers embedded in frit.
- 1 3. The display element according to claim 1, further
2 comprising a rib structure formed on the bottom surface of
3 the glass cap, surrounded by the sealing layer and surrounding
4 the luminescent body.
- 1 4. The display element according to claim 3, wherein the
2 rib structure is frit.
- 1 5. The display element according to claim 3, wherein the
2 rib structure is of ceramic materials.
- 1 6. The display element according to claim 1, further
2 comprising a concavity on the bottom surface of the glass cap
3 and positioned corresponding to the luminescent body.

1 7. The display element according to claim 1, wherein the
2 display element is used in an organic light emitting diode
3 (OLED).

1 8. The display element according to claim 1, wherein the
2 display element is used in a plastic light emitting diode
3 (PLED).

1 9. The display element according to claim 1, wherein the
2 luminescent body is at least laminated with an anode layer,
3 an organic luminescent layer and a cathode layer.

1 10. A method of encapsulating a display element,
2 comprising steps of:

3 providing a display element, which has a luminescent body
4 formed on a glass substrate, a glass cap with the rim bonded
5 to the rim of the glass substrate, and a sealing layer of frit
6 formed on the bonding region between the glass substrate and
7 the glass cap;

8 providing a pedestal on which the display element is
9 placed;

10 providing a pressing plate disposed on the display
11 element;

12 providing a high-power beam which penetrates the glass cap
13 to focus on the sealing layer so as to sinter frit; and

14 applying pressure on the pedestal and the pressing plate.

1 11. The method of encapsulating the display element
2 according to claim 10, wherein the pedestal and the pressing
3 plate are metal materials with good thermal conductivity.

1 12. The method of encapsulating the display element
2 according to claim 10, wherein the high-power beam is a laser
3 beam.

1 13. The method of encapsulating the display element
2 according to claim 12, wherein the laser beam has a wavelength
3 of more than 550nm.

1 14. The method of encapsulating the display element
2 according to claim 10, wherein the high-power beam is an
3 infrared ray.

1 15. The method of encapsulating the display element
2 according to claim 14, wherein the infrared ray has a
3 wavelength of more than 800nm.

1 16. The method of encapsulating the display element
2 according to claim 10, wherein the sealing layer comprises
3 spacers embedded in frit.

1 17. The method of encapsulating the display element
2 according to claim 10, wherein the display element comprises
3 a rib structure formed on the bottom surface of the glass cap,
4 surrounded by the sealing layer and surrounding the
5 luminescent body.

1 18. The method of encapsulating the display element
2 according to claim 17, wherein the rib structure is frit.

1 19. The method of encapsulating the display element

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2 according to claim 17, wherein the rib structure is of ceramic
3 materials.

1 20. The method of encapsulating the display element
2 according to claim 10, the display element comprises a
3 concavity formed on the bottom surface of the glass cap and
4 positioned corresponding to the luminescent body.

1 21. The method of encapsulating the display element
2 according to claim 10, wherein the display element is used
3 in an organic light emitting diode (OLED).

1 22. The method of encapsulating the display element
2 according to claim 10, wherein the display element is used
3 in a plastic light emitting diode (PLED).

1 23. The method of encapsulating the display element
2 according to claim 10, wherein the luminescent body is at
3 least laminated with an anode layer, an organic luminescent
4 layer and a cathode layer.